

ABSTRACT
SUBSTRATE POLISHING APPARATUS

According to an aspect of the present disclosure, a substrate polishing apparatus including a turntable for supporting a polishing pad, a dresser that dresses the polishing pad, a dresser drive module that presses the dresser against the polishing pad and rotates the dresser, a support member that supports the dresser drive module, and a plurality of force sensors which are provided between the dresser drive module and the support member and each of which outputs information related to each of forces in three axis directions is provided.

Figure 2